

Bill of Materials

TI DESIGNS
TIPD136: Active Volume Control

Item #	Quantity	Value	Designator	Description	Manufacturer	Part Number	Supplier Part Number
1	2	100pF	C1, C6	CAP CER 100PF 1KV 10% X7R 1206	Johanson Dielectrics Inc	102R18W101KV4E	709-1294-1-ND
2	2	0.1uF	C2, C4	CAP CER 0.1UF 50V 10% X7R 0603	TDK Corporation	C1608X7R1H104K080AA	445-1314-1-ND
3	4	22uF	C3, C7-C9	CAP CER 22UF 25V 10% X7R 1210	Samsung Electro-Mechanics	CL32B226KAJNNNE	1276-3392-1-ND
4	1	3.3nF	C5	CAP CER 0.033UF 50V 5% NP0 1206	Samsung Electro-Mechanics	CL31C333JBHNNWE	1276-3261-1-ND
5	1	TVS	D1	DIODE TVS 15V 600W BI 5% SMD	Bourns	SMBJ15CA	SMBJ15CABCT-ND
6	1	10kΩ	R2	RES 10K OHM 1/4W 1% 1206	Stackpole Electronics	RMCF1206FT10K0	RMCF1206FT10K0CT-ND
7	4	1kΩ	R3, R4, R8, R9	RES 1K OHM 1/4W 1% 1206	Stackpole Electronics	RMCF1206FT1K00	RMCF1206FT1K00CT-ND
8	1	100Ω	R5	RES 100 OHM 1/4W 1% 1206	Stackpole Electronics	RMCF1206FT100R	RMCF1206FT100RCT-ND
9	1	220kΩ	R6	RES 220K OHM 1/4W 1% 1206 SMD	Panasonic Electronic Components	ERJ-8ENF2203V	P220KFCT-ND
10	1	100kΩ	R7	RES 100K OHM 1/4W 1% 1206	Stackpole Electronics	RMCF1206FT100K	RMCF1206FT100KCT-ND
11	1	22kΩ	R10	RES 22K OHM 1/4W 1% 1206 SMD	Panasonic Electronic Components	ERJ-8ENF2202V	P22.0KFCT-ND
12	1	10kΩ POT	P1	10K LINEAR POT	Alpha	RV16AF-20-15R1-B10K-00	RV16AF-20-15R1-B10K-00H4
13	1	OPA1604	U1	OPA1604 SOUND-PLUS OP AMP	Texas Instruments	OPA1604AID	N/A
14	2	RCA	J1, J4	CONN RCA JACK METAL R/A BLK PCB	CUI Inc	RCJ-011	CP-1400-ND
15	3	BANANA	J2, J3, J5	CONN JACK BANANA UNINS PANEL MOU	Emerson Network Power	108-0740-001	J147-ND
16	4	SCREW	Screws	SCREW MACHINE PHILLIPS 4-40X3/8	B&F Fastener Supply	PMS 440 0038 PH	H781-ND
17	4	STANDOFF	Standoffs	STANDOFF HEX 4-40THR ALUM .500"L	Keystone Electronics	2203	2203K-ND
18	2	DNP	R1, R11	DO NOT POPULATE	N/A	N/A	N/A

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